

ABSTRACT OF THE DISCLOSURE

A method of manufacturing a package is disclosed. The manufacturing method includes the steps of providing a substrate having an opening, disposing a metal slice on a bottom surface of the substrate to cover the opening and bond pads on the bottom surface of the substrate, disposing a
5 die on the metal slice inside the opening or above the top surface of the substrate outside the opening, forming a number of bond wires between the top surface of the die and the top surface of the substrate to electrically connect the die to the substrate, forming an encapsulating mold compound to
10 cover the die, the bond wires, and a part of the top surface of the substrate, removing a part of the metal slice to form a metal heat slug thermally connected to the die and to expose the bond pads, and forming a number of solder balls on the exposed bond pads.

* * * * *